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(71) Applicant (for all designated States except US): **SILVERBROOK RESEARCH PTY. LTD.** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU).

(72) Inventor; and

(75) Inventor/Applicant (for US only): **SILVERBROOK, Kia** [AU/AU]; Silverbrook Research Pty Ltd, 393 Darling Street, Balmain, New South Wales 2041 (AU).

(74) Agent: **SILVERBROOK, KIA**; Silverbrook Research Pty Ltd, 393 Darling Street, Balmain, New South Wales 2041 (AU).

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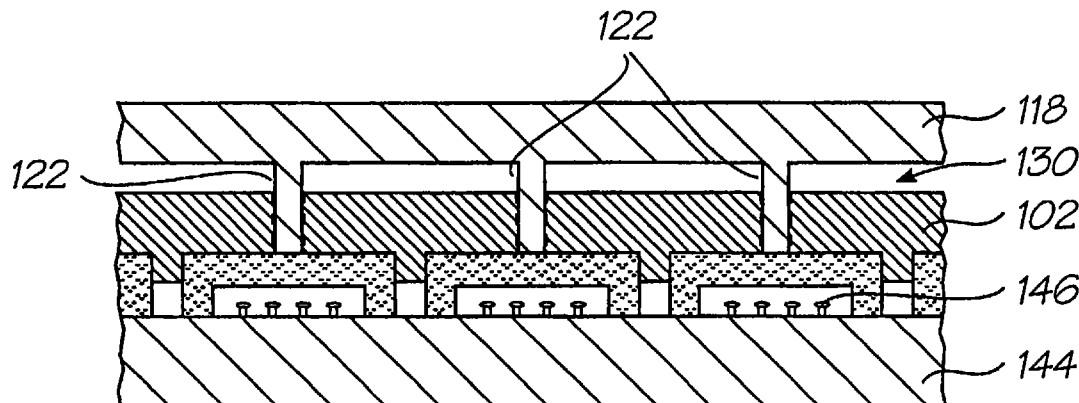
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(54) Title: WAFER SCALE MOLDING OF PROTECTIVE CAPS



(57) Abstract: The invention is a method of applying an array (134) of caps to a wafer (144) of semiconductor material which includes a plurality of microfabricated devices (146). The method includes applying the array (134) of first caps substantially simultaneously to one side of the wafer (144), bonding the array (134) of caps to the wafer (144) and then separating the wafer into individual packages (148).